

AMENDMENTS

In The Specification

Please amend the specification as follows.

⁹
[0036] In conclusion, the invention at least has the following advantages:

B¹
1. Since each bump is surrounded by conductive paste, electric current is able to pass from the bump to the solder ball via the conductive paste. Because conductive paste has good extensibility, thermal stress caused by deformation between the chip and the circuit board caused by heat is annulled. Hence, contact failure due to bump breakage in a conventional package design is entirely avoided.

2. The final cutout package has a relatively small volume, and the sectional area of the package is almost identical to the sectional area of the chip. Moreover, the bumps are enclosed inside the open windows of the insulation layer so that overall thickness of the package is reduced.

3. The wafer level package structure and manufacturing procedure can reduce the production cost.

In The Claims

Please amend the claims as follows.

B²
9. (Once amended) A process of forming an insulation layer having a plurality of conductive paste plugs therein over a wafer, comprising the steps of:
providing a wafer having a plurality of chips therein, wherein the wafer has an active side;
forming an insulation layer over the active side of the wafer;